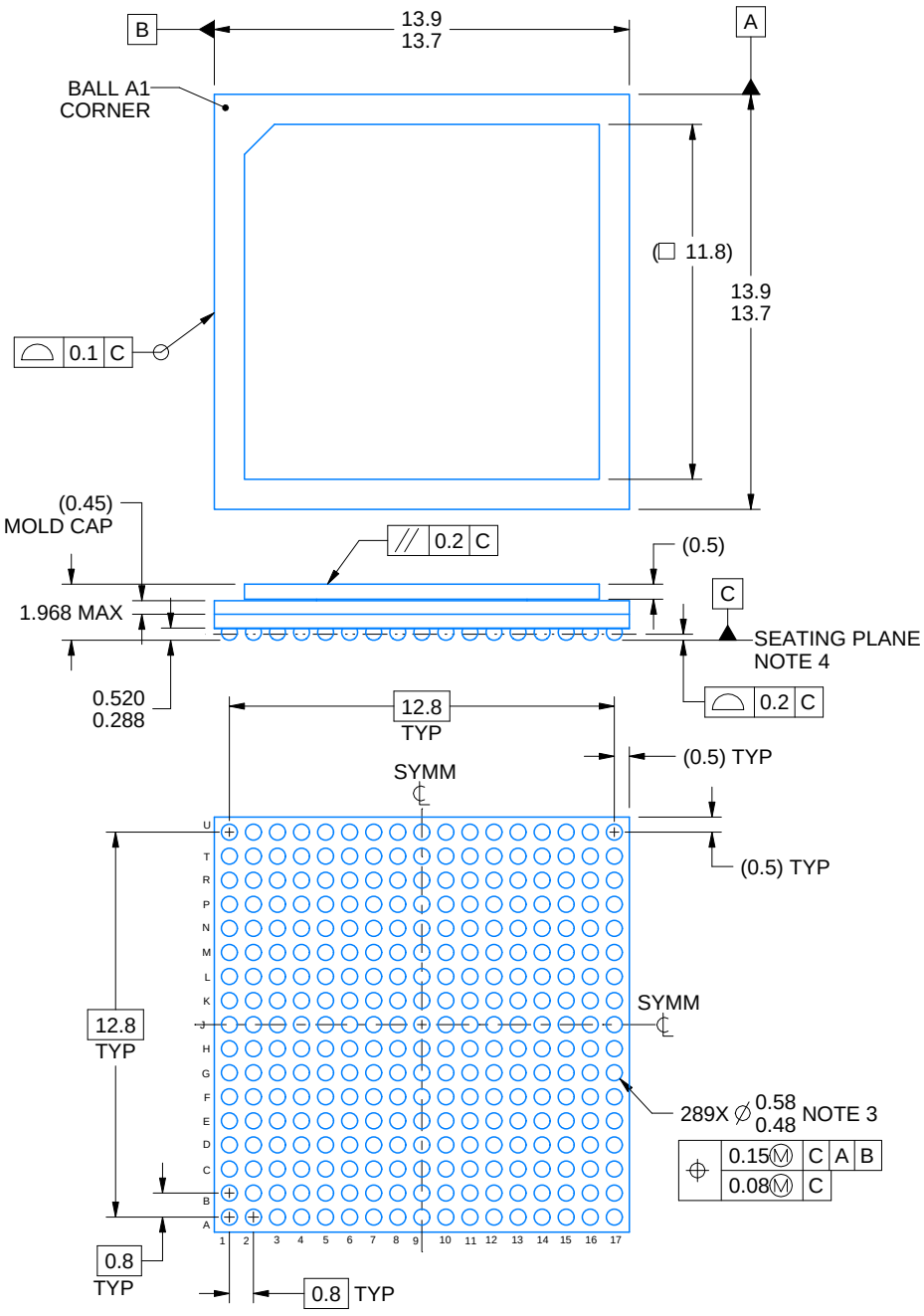
PACKAGE OUTLINE

ANH0289A

FCCSP - 1.968 mm max height

BALL GRID ARRAY



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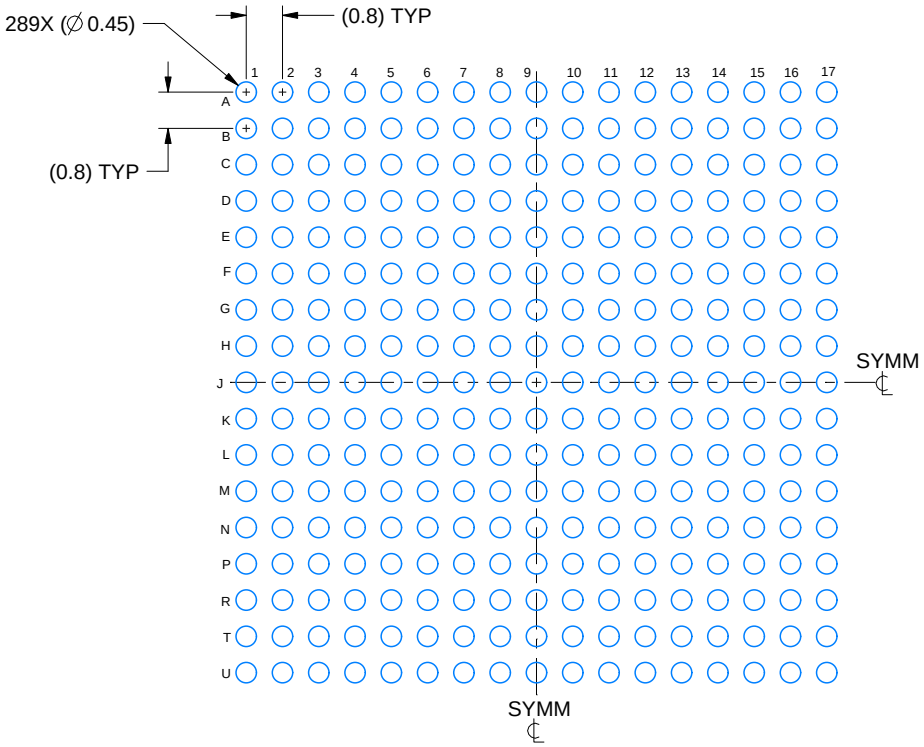
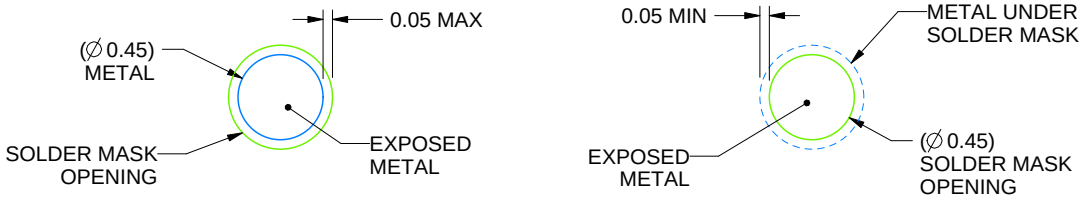
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Dimension is measured at the maximum solder ball diameter, post reflow, parallel to primary datum C.
4. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 6X



SOLDER MASK DETAILS
NOT TO SCALE

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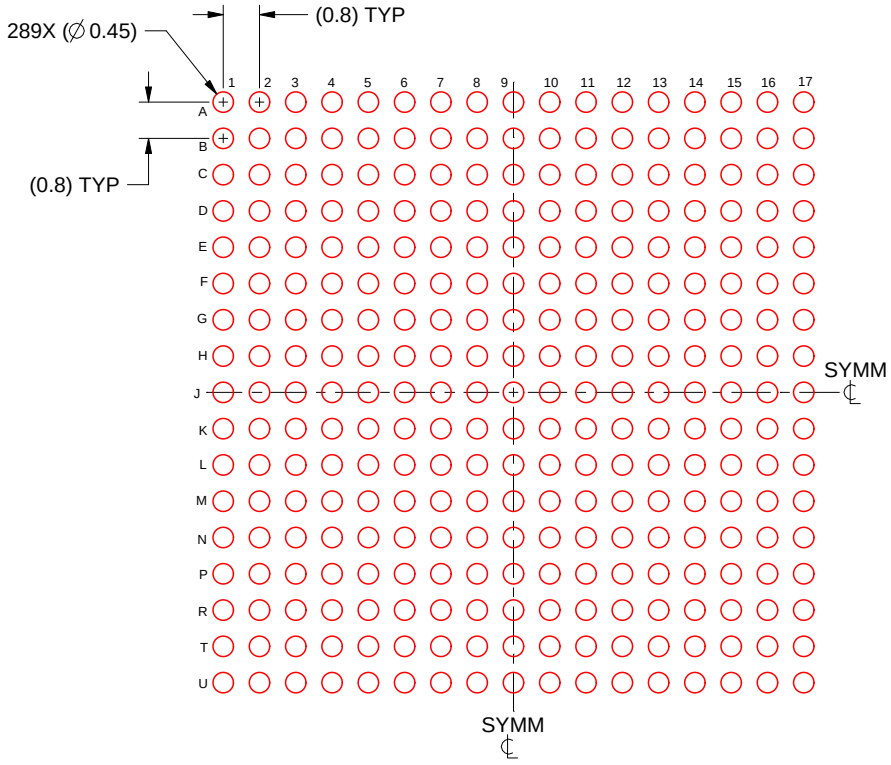
NOTES: (continued)

5. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
See Texas Instruments Literature No. SPRU811 (www.ti.com/lit/spru811).



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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